

2SJ0536G

Silicon P-channel MOSFET

Secondary battery packs (Li ion battery, etc.)

For switching circuits

■ Features

- High-speed switching
- S-mini type package, allowing downsizing of the sets and automatic insertion through the tape/magazine packing
- Low voltage drive (V_{th} : -1.0 V to 2.0 V)
- Low ON resistance

■ Package

- Code
SMini3-F2
- Marking Symbol: 2C
- Pin Name
1: Gate
2: Source
3: Drain

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

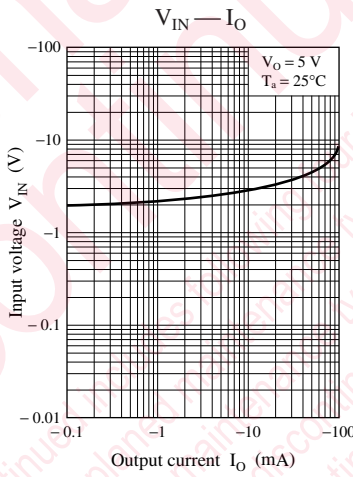
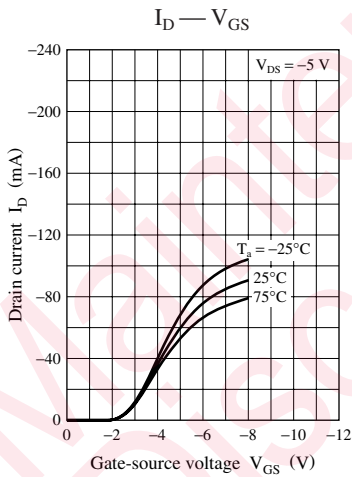
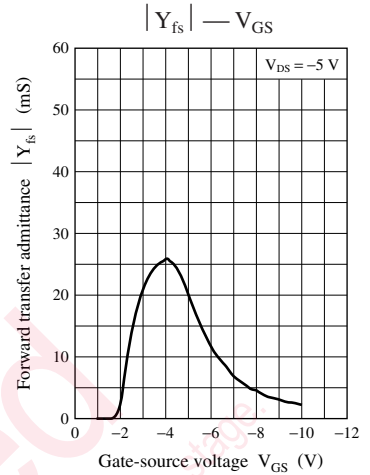
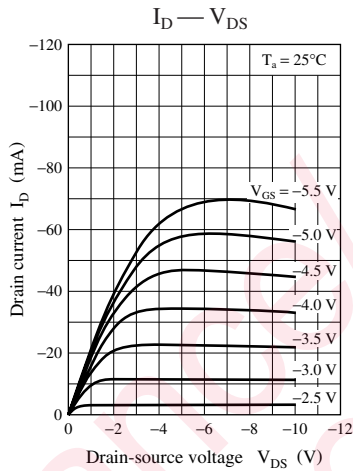
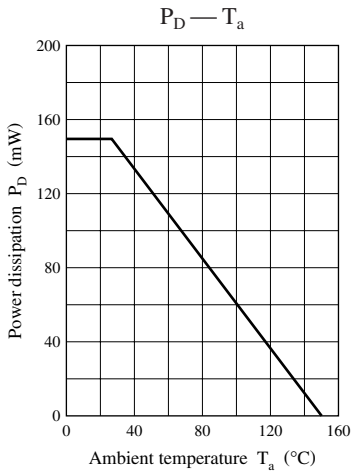
Parameter	Symbol	Rating	Unit
Drain-source surrender voltage	V_{DSS}	-30	V
Gate-source voltage (Drain open)	V_{GSO}	± 20	V
Drain current	I_D	-100	mA
Peak drain current	I_{DP}	-200	mA
Power dissipation	P_D	150	mW
Channel temperature	T_{ch}	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to $+150$	$^\circ\text{C}$

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-source cutoff current	I_{DSS}	$V_{DS} = -30$ V, $V_{GS} = 0$			-0.1	μA
Gate-source cutoff current	I_{GSS}	$V_{GS} = \pm 20$ V, $V_{DS} = 0$			± 1.0	μA
Gate threshold voltage	V_{th}	$V_{DS} = -5$ V, $I_D = -1$ μA	-1.0		-2.0	V
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = -5$ V, $I_D = -10$ mA	8			mS
Drain-source ON resistance	$R_{DS(on)}$	$V_{GS} = -5$ V, $I_D = -10$ mA		50	75	Ω
Turn-on time	t_{on}	$V_{DD} = -5$ V, $V_{GS} = 0$ V ~ -5 V $R_L = 200$ Ω		100		μs
Turn-off time	t_{off}	$V_{DD} = -5$ V, $V_{GS} = -5$ V ~ 0 V $R_L = 200$ Ω		25		μs

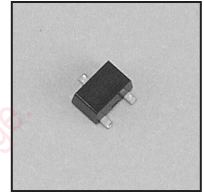
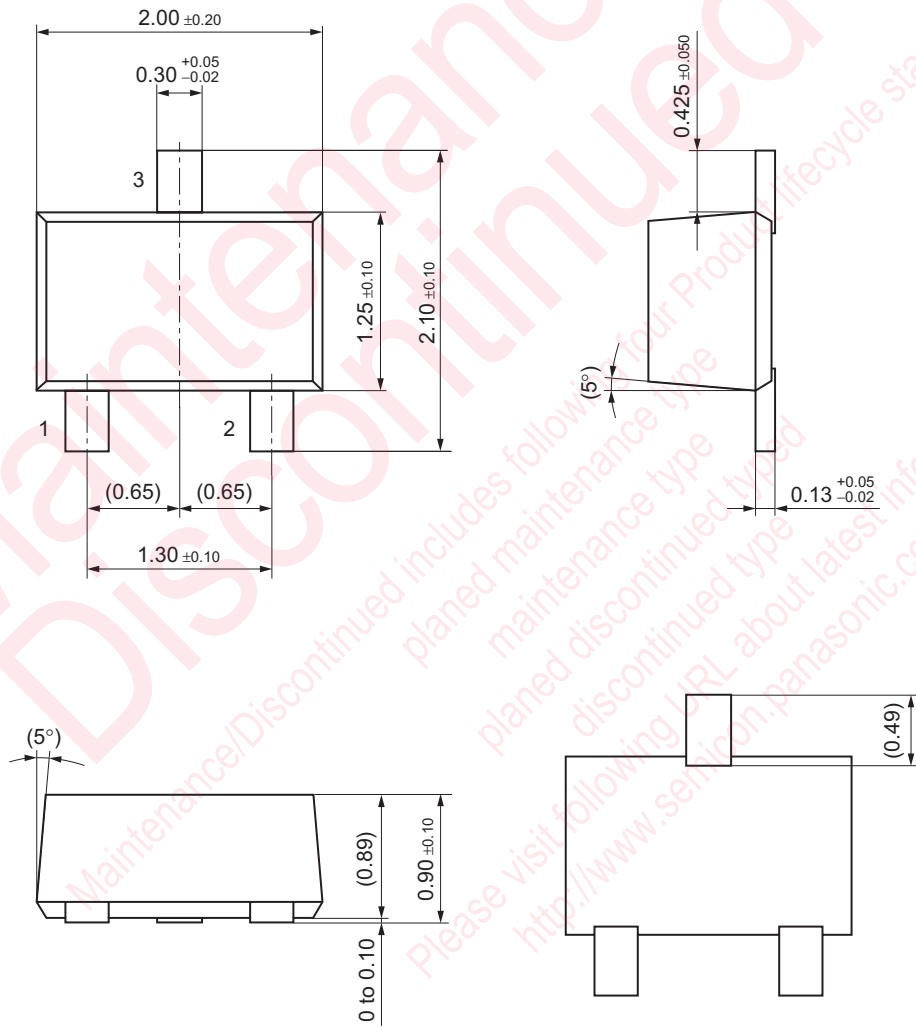
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. Observe precautions for handling. Electrostatic sensitive devices.



SMini3-F2

Unit: mm



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